



As an inventor named below or on any attached continuation page, I hereby declare that:

My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled SEMICONDUCTOR SUBSTRATE-BASED BGA INTERCONNECTION AND METHODS OF FABRICATING SAME, the specification of which (check one):

is attached hereto.			•				
	as United States application serial no and was amended on as PCT international application no and was amended under PCT Article 19 on						
was filed on as PCT i	international application no.	and was ame	nded under PCT	Article 19 on	<del></del> •		
I hereby state that I have reviewed and referred to above.	understand the contents of the above	-identified specific	eation, including	the claims, as amend	ied by any ar	mendment	
I acknowledge the duty to disclose to the				material to the pater	ntability of th	e subject	
matter claimed in this application, as "mate	riality" is defined in Title 37, Code of	of Federal Regula	tions § 1.50.				
I hereby claim foreign priority benefits certificate or § 365(a) of any PCT internation attached continuation page and have also id any PCT international application(s) design.	onal application(s) designating at lease entified below and on any attached c	st one country oth continuation page	er than the Unite any foreign appl	ed States of America ication for patent or i	listed below a	and on any rtificate or	
on which priority is claimed.							
Prior foreign/PCT application(s):		(2)		Priority Claimed			
(number)	(country	7	(day)	month/year filed)	Yes	No	
(numous)	(vout)		(02),	monum your mooy	103	110	
(number)	(country	)	(day)	month/year filed)	Yes	No	
duty to disclose to the U.S. Patent and Trad Regulations § 1.56 which became available (application serial no.)			he national or Po		g date of this		
(application serial no.)	(timing duto)	(iming ture)					
(application serial no.)	(filing date)	<del></del>	(status - pe	ending, patented or a	bandoned)	<del></del>	
I hereby claim the ben	efit under Title 35, United States Co	ode, § 119(e) of a	ny United States	provisional applicati	on(s) listed b	elow:	
(provisional application no.)	(filing date)	<del>i jira iz</del>					
(provisional application no.)	(filing date)						
(provisional application no.)	(filing date)	<del></del>					
I hereby appoint the following Registered therewith:	Practitioners to prosecute this appli	cation and to tran	sact all business	in the Patent and Tra	ademark Offic	ce connected	
David V. Trask, Reg. No. 22,012 Laurence B. Bond, Reg. No. 30,549 Allen C. Turner, Reg. No. 33,041 Robert G. Winkle, Reg. No. 37,474 Brick G. Power, Reg. No. 38,581 Lia M. Pappas, Reg. No. 34,095	William S. Britt, Reg. No. 20, Joseph A. Walkowski, Reg. N Kent S. Burningham, Reg. No Patrick McBride, Reg. No. 39 Kenneth C. Booth, Reg. No. 4	o. 28,765 . 30,453 ,295	Thomas J. Rossa, Reg. No. 26,799 James R. Duzan, Reg. No. 28,393 Julie K. Morriss, Reg. No. 33,263 Edgar R. Cataxinos, Reg. No. 39,931 Michael L. Lynch, Reg. No. 30,871				
TR P.C	eph A. Walkowski, telephone no. (8 ASK, BRITT & ROSSA ). BOX 2550 t Lake City, Utab 84110	801) 532-1922.		·			
I hereby declare that all statements made and further that these statements were made whoth, under Section 1001 of Title 18 of the Uissued increon.	vith the knowledge that willful false inited States Code and that such will	statements and th Iful false statemen	e like so made a	re punishable by fine	or imprison	ment, or	
Full name of sole inventor: Salman Akram Inventor's signature	Salvan Dhram	Λ Date	9/3	23 98		· 	
Residence: Boise, Idaho Citizenship: Pakistan				1			

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## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Salman Akram

Serial No.: 09/649,225

**Filed:** August 28, 2000

For: METHODS OF FABRICATING SEMICONDUCTOR SUBSTRATE-BASED BGA INTERCONNECTION (Amended)

Confirmation No.: 6839

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Person making Deposit:

Matthew Wooton

## ASSOCIATE POWER OF ATTORNEY (37 C.F.R. § 1.34(b))

Commissioner for Patents Washington, D.C. 20231

Sir:

In accordance with 37 C.F.R. § 1.34(b), please recognize the following individual as an associate agent/attorney herein in connection with the above-identified patent application, and with all continuing and divisional applications hereof:

Tawni L. Wilhelm, Reg. No. 47,456

## Serial No. 09/649,225

Respectfully submitted,

Joseph A. Walkowski

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Attorney for Applicant(s)

**TRASKBRITT** 

P.O. Box 2550

Date: April 11, 2003

TLW/ps:ah
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